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JSR Develops and Launches an Insulation Material for 5G High Speed Transmission

JSR Corporation (CEO: Eric Johnson) is pleased to announce that it has developed and launched an insulation material with a low dielectric constant and low dissipation factor for use in high frequency printed circuit boards for 5th Generation Mobile Communication Systems (5G).

The main features of this insulation material are as follows;- Maintains good electric properties in hot and humid conditions.- Possesses high adhesiveness to the base film of Flexible Copper Clad Laminate (FCCL) and low roughened copper foil.- Thermosetting material with high resin fluidity which enables excellent embeddedness of lines and processability under 200°C using a standard facility.- Possesses excellent processability of via hole of printed circuit board and good adhesiveness to plating.

Low Loss TPE (Thermosetting Polyether) FCCL using this insulation material will be exhibited at the 5G/IoT Network Expo held at Tokyo Big Site, July 17-19, 2019.



JSR Micro